

## CLAIMS

What is claimed is:

- 1 1. A method comprising:  
2 forming a thin, flexible substrate having a conductor region adapted to  
3 mount an integrated circuit;  
4 forming a plurality of traces in the conductor region; and  
5 forming a plurality of lands coupled to the traces.
- 1 2. The method recited in claim 1, wherein the substrate is formed of material  
2 from the group comprising a polymeric film, polyimide, polyester, polyparabanic  
3 acid, epoxy, and fiberglass.
- 1 3. The method recited in claim 1, wherein forming the substrate comprises  
2 forming a plurality of layers, each comprising a plurality of traces in the conductor  
3 region.
- 1 4. The method recited in claim 1, wherein forming the substrate comprises  
2 forming a plurality of sprocket holes outside the conductor region.
- 1 5. The method recited in claim 1, wherein the lands are arranged in a ball grid  
2 array, the method further comprising:  
3 forming solder balls on the plurality of lands.
- 1 6. A method comprising:  
2 forming a thin, flexible substrate having a conductor region comprising a  
3 plurality of traces and a plurality of lands coupled to the plurality of traces; and  
4 coupling pads on an integrated circuit (IC) to corresponding lands on the  
5 substrate.

- 1 7. The method recited in claim 6, wherein the substrate is formed of material  
2 from the group comprising a polymeric film, polyimide, polyester, polyparabanic  
3 acid, epoxy, and fiberglass.
- 1 8. The method recited in claim 6, wherein forming the substrate comprises  
2 forming a plurality of layers, each comprising a plurality of traces in the conductor  
3 region.
- 1 9. The method recited in claim 6, wherein forming the substrate comprises  
2 forming a plurality of sprocket holes outside the conductor region.
- 1 10. The method recited in claim 6 and further comprising before coupling:  
2 forming solder balls on the lands.
- 1 11. The method recited in claim 6 and further comprising:  
2 mounting the substrate on an additional substrate.
- 1 12. The method recited in claim 11, wherein the additional substrate comprises  
2 a printed circuit board.
- 1 13. The method recited in claim 11, wherein lands are coupled to corresponding  
2 terminals on the additional substrate.
- 1 14. The method recited in claim 12 and further comprising before mounting:  
2 forming solder balls on the lands.
- 1 15. The method recited in claim 12, wherein the lands are coupled to the  
2 terminals using a ball grid array.

1 16. The method recited in claim 12, wherein leads are coupled between  
2 corresponding lands and terminals.

1 17. An electronic package substrate comprising:  
2 a thin, flexible, electrically insulating film having a conductor region  
3 adapted to mount an integrated circuit;  
4 a plurality of traces in the conductor region; and  
5 a plurality of lands coupled to the traces.

1 18. The electronic package substrate recited in claim 17, wherein the film is  
2 formed of material from the group comprising a polymeric film, polyimide,  
3 polyester, polyparabanic acid, epoxy, and fiberglass.

1 19. The electronic package substrate recited in claim 17, wherein the film  
2 comprises a plurality of layers, each comprising a plurality of traces in the  
3 conductor region.

1 20. The electronic package substrate recited in claim 17, wherein the lands are  
2 arranged in a ball grid array.

1 21. An electronic package comprising:  
2 an electrically insulating film having a thickness in the range of  
3 approximately .15 to .90 millimeters, the film having a conductor region, a plurality  
4 of traces in the conductor region, and a plurality of lands coupled to the traces; and  
5 an electronic component having a plurality of pads coupled to the plurality  
6 of lands.

1 22. The electronic package recited in claim 21, wherein the film is formed of  
2 material from the group comprising a polymeric film, polyimide, polyester,  
3 polyparabanic acid, epoxy, and fiberglass.

1 23. The electronic package recited in claim 21, wherein the film comprises a  
2 plurality of layers, each comprising a plurality of traces in the conductor region, and  
3 wherein each layer has a thickness within the range of approximately .15 to .30  
4 millimeters.

1 24. The electronic package recited in claim 21, wherein the lands are arranged in  
2 a ball grid array.

1 25. The electronic package recited in claim 21, wherein the electronic  
2 component comprises an integrated circuit.

3 26. An electronic system comprising at least one electronic assembly  
4 comprising:  
5 a thin, flexible, electrically insulating film having a conductor region, a  
6 plurality of traces in the conductor region, and a plurality of lands coupled to the  
7 traces; and  
8 an electronic component having a plurality of pads coupled to the plurality  
9 of lands.

1 27. The electronic system recited in claim 26, wherein the film is formed of  
2 material from the group comprising a polymeric film, polyimide, polyester,  
3 polyparabanic acid, epoxy, and fiberglass.

1 28. The electronic system recited in claim 26, wherein the film comprises a  
2 plurality of layers, each comprising a plurality of traces in the conductor region.

1 29. The electronic system recited in claim 26, wherein the lands are arranged in  
2 a ball grid array.

1 30. The electronic system recited in claim 26, wherein the electronic component  
2 comprises an integrated circuit.

1 31. A data processing system comprising:  
2 a bus coupling components in the data processing system;  
3 a display coupled to the bus;  
4 a memory coupled to the bus; and  
5 a processor coupled to the bus and comprising an electronic assembly  
6 including,  
7 a thin, flexible electrically insulating film having a conductor region,  
8 a plurality of traces in the conductor region, and a plurality of lands coupled  
9 to the traces; and  
10 an integrated circuit having a plurality of pads coupled to the  
11 plurality of lands.

1 32. The data processing system recited in claim 31, wherein the film is formed  
2 of material from the group comprising a polymeric film, polyimide, polyester,  
3 polyparabanic acid, epoxy, and fiberglass.

1 33. The data processing system recited in claim 31, wherein the film comprises a  
2 plurality of layers, each comprising a plurality of traces in the conductor region.

1 34. The data processing system recited in claim 31, wherein the lands are  
2 arranged in a ball grid array.